Materials Declaration

Package	TSSOP
Body Size	4.4
LeadCount	24
Option	Pb-Free

Molding Compound

Item	% of Compound	Weight (g)	PPM
SiO2 Filler	85	3.66 E-02	446540
Biphenyl resin	14.15	6.03 E-03	73548
Antimony_Sb2O3	0.5	2.15 E-04	2627
Brominated Resin	0.35	1.51 E-04	1839
Subtotal		4.30 E-02	524553

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	96.2	2.68 E-02	327733
Ni	3	8.37 E-04	10220
Si	0.65	1.81 E-04	2214
Mg	0.15	4.19 E-05	511
Subtotal		2.79 E-02	340679

Internal Leadframe Plating

	% of Plating	Weight (g)	PPM
Ag	100	1.28 E-03	15678

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	100	2.19 E-03	26732

Bond Wires

	% of Wire	Weight (g)	PPM
Au	99.99	1.01 E-03	12327

Chip

	% of Chip	Weight (g)	PPM
Si	100	5.22 E-03	63763

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Ag Filler	75	1.00 E-03	12201
Resin	20	2.67 E-04	3254
Aromatic Amine	5	6.66 E-05	813
Subtotal		1.33 E-03	16269

Package Totals

Weight (g)	PPM
8.19 E-02	1000000

Molding Compound

Item	PPM	Method
Pb	Not Detected	EPA Method 3051A /3052. ICP-OES
Cd	Not Detected	EPA Method 3051A /3052. ICP-OES
Hg	Not Detected	EPA Method 3051A /3052. ICP-OES
Cr+6	Not Detected	EPA Method 3060A & 7196A. UV-VIS
PBB	Not Detected	EPA Method 3540C/3550C. GC/MS
PBDE	Not Detected	EPA Method 3540C/3550C. GC/MS

Die Attach Paste

Item	PPM	Method
Pb	Not Detected	EPA Method 3051A /3052. ICP-OES
Cd	Not Detected	EPA Method 3051A /3052. ICP-OES
Hg	Not Detected	EPA Method 3051A /3052. ICP-OES
Cr+6	Not Detected	EPA Method 3060A & 7196A. UV-VIS
PBB	Not Detected	EPA Method 3540C/3550C. GC/MS
PBDE	Not Detected	EPA Method 3540C/3550C. GC/MS

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability tc
any inaccuracy of such information.

ADI Proprietary

Materials Declaration

Package	TSSOP
Body Size	4.4
LeadCount	24
Option	Sn/Pb

Molding Compound

Item	% of Compound	Weight (g)	PPM
SiO2 Filler	85	3.66 E-02	446540
Biphenyl resin	14.15	6.03 E-03	73548
Antimony_Sb2O3	0.5	2.15 E-04	2627
Brominated Resin	0.35	1.51 E-04	1839
Subtotal		4.30 E-02	524553

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	96.2	2.68 E-02	327733
Ni	3	8.37 E-04	10220
Si	0.65	1.81 E-04	2214
Mg	0.15	4.19 E-05	511
Subtotal		2.79 E-02	340679

Internal Leadframe Plating

	% of Plating	Weight (g)	PPM
Ag	100	1.28 E-03	15678

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	85	1.86 E-03	22722
Pb	15	3.29 E-04	4010
Subtotal		2.19 E-03	26732

Bond Wires

	% of Wire	Weight (g)	PPM
Au	99.99	1.01 E-03	12327

Chip

	% of Chip	Weight (g)	PPM
Si	100	5.22 E-03	63763

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Ag Filler	75	1.00 E-03	12201
Resin	20	2.67 E-04	3254
Aromatic Amine	5	6.66 E-05	813
Subtotal		1.33 E-03	16269

Package Totals

Weight (g)	PPM
8.19 E-02	1000000

Molding Compound

Item	PPM	Method
Pb	Not Detected	EPA Method 3051A /3052. ICP-OES
Cd	Not Detected	EPA Method 3051A /3052. ICP-OES
Hg	Not Detected	EPA Method 3051A /3052. ICP-OES
Cr+6	Not Detected	EPA Method 3060A & 7196A. UV-VIS
PBB	Not Detected	EPA Method 3540C/3550C. GC/MS
PBDE	Not Detected	EPA Method 3540C/3550C. GC/MS

Die Attach Paste

Item	PPM	Method
Pb	Not Detected	EPA Method 3051A /3052. ICP-OES
Cd	Not Detected	EPA Method 3051A /3052. ICP-OES
Hg	Not Detected	EPA Method 3051A /3052. ICP-OES
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PBB	Not Detected	EPA Method 3540C/3550C. GC/MS
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